

## N-Channel Enhancement Mode Power MOSFET

### Description

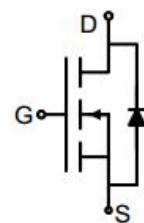
This advanced MOSFET family has optimized on-state resistance, and also provides superior switching performance and higher avalanche energy strength. This device family is suitable for high efficiency switch mode power supplies.

### General Features

- $V_{DS}$  500V
- $I_D$  (at  $V_{GS} = 10V$ ) 18A
- $R_{DS(ON)}$  (at  $V_{GS} = 10V$ ) < 0.35Ω
- 100% Avalanche Tested
- RoHS Compliant
- Low Crss (typical 4.3pF)
- Fast switching capability
- Improved dv/dt capability

### Application

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC) (PFC)
- Charger



Schematic diagram



TO-220

### Ordering Information

Device	Package	Marking	Packaging
G18N50T	TO-220	G18N50	50pcs/Tube

### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	500	V
Continuous Drain Current	$I_D$	18	A
Pulsed Drain Current (note1)	$I_{DM}$	72	A
Gate-Source Voltage	$V_{GS}$	$\pm 30$	V
Power Dissipation	$P_D$	189.3	W
Single pulse avalanche energy (note2)	$E_{AS}$	180	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 To 150	°C

### Thermal Resistance

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	62	°C/W
Maximum Junction-to-Case	$R_{thJC}$	0.66	°C/W

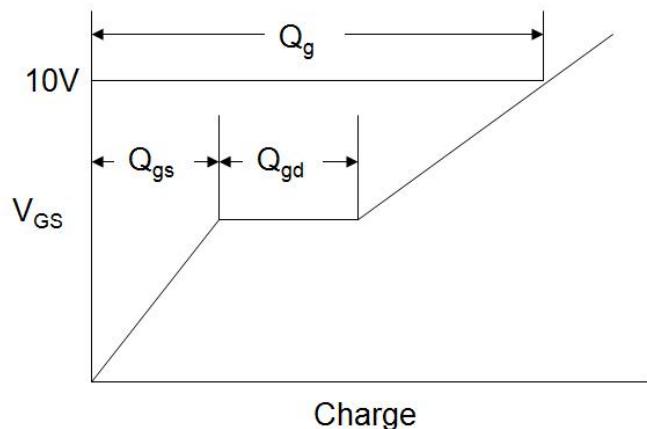
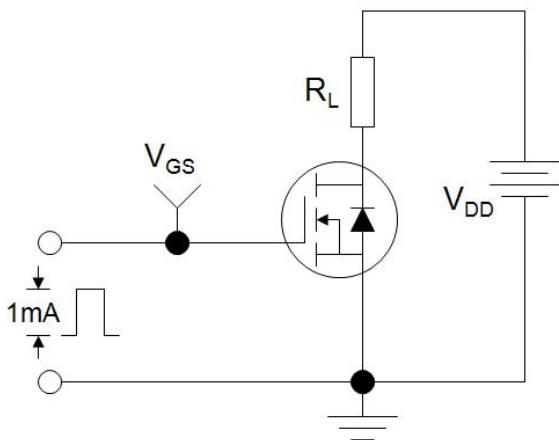
**Specifications**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	500	--	--	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 500\text{V}, V_{\text{GS}} = 0\text{V}$	--	--	1	$\mu\text{A}$
Gate-Source Leakage	$I_{\text{GSS}}$	$V_{\text{GS}} = \pm 30\text{V}$	--	--	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	3.0	4.0	5.0	V
Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 9\text{A}$	--	0.28	0.35	$\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{GS}} = 5\text{V}, I_D = 9\text{A}$	--	16	--	S
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 250\text{V}, f = 1.0\text{MHz}$	--	3000	--	pF
Output Capacitance	$C_{\text{oss}}$		--	73	--	
Reverse Transfer Capacitance	$C_{\text{rss}}$		--	7	--	
Total Gate Charge	$Q_g$	$V_{\text{DD}} = 250\text{V}, I_D = 9\text{A}, V_{\text{GS}} = 10\text{V}$	--	50	--	nC
Gate-Source Charge	$Q_{\text{gs}}$		--	18	--	
Gate-Drain Charge	$Q_{\text{gd}}$		--	12	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 250\text{V}, I_D = 9\text{A}, R_G = 10\Omega$	--	28	--	ns
Turn-on Rise Time	$t_r$		--	47	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	57	--	
Turn-off Fall Time	$t_f$		--	40	--	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Body Diode Current	$I_S$	$T_C = 25^\circ\text{C}$	--	--	18	A
Body Diode Voltage	$V_{\text{SD}}$	$T_J = 25^\circ\text{C}, I_{\text{SD}} = 9\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	1.2	V
Reverse Recovery Charge	$Q_{\text{rr}}$	$I_F = 9\text{A}, V_{\text{GS}} = 0\text{V}$ $dI/dt = 100\text{A}/\mu\text{s}$	--	5	--	nC
Reverse Recovery Time	$T_{\text{rr}}$		--	449	--	ns

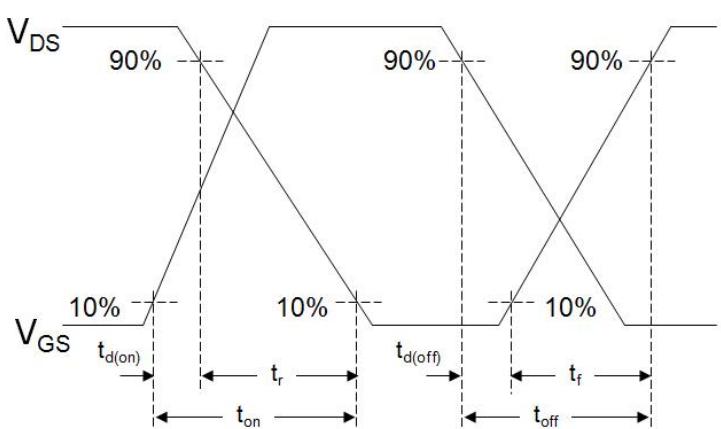
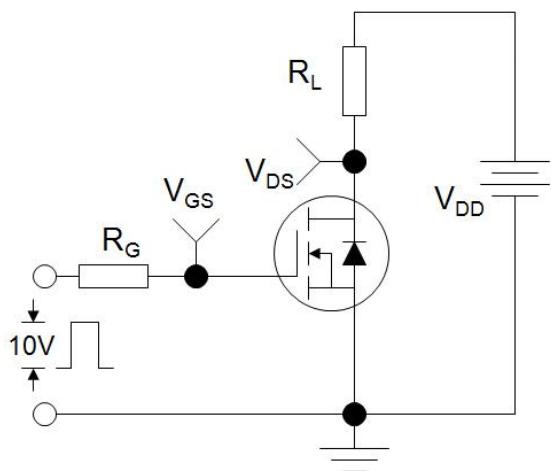
**Notes**

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. EAS condition :  $T_J=25^\circ\text{C}$ ,  $V_{\text{DD}}=50\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=10\text{mH}$ ,  $R_g=25\Omega$
3. Identical low side and high side switch with identical  $R_G$

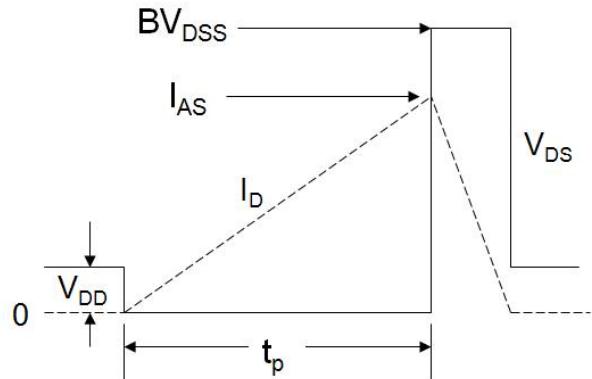
### Gate Charge Test Circuit



### Switch Time Test Circuit

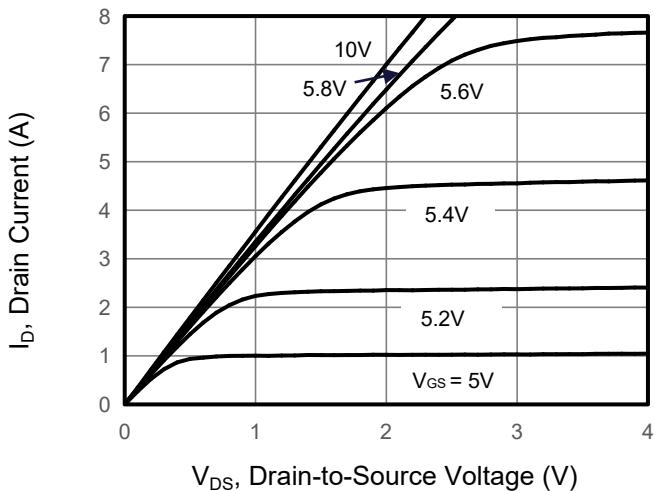


### EAS Test Circuit

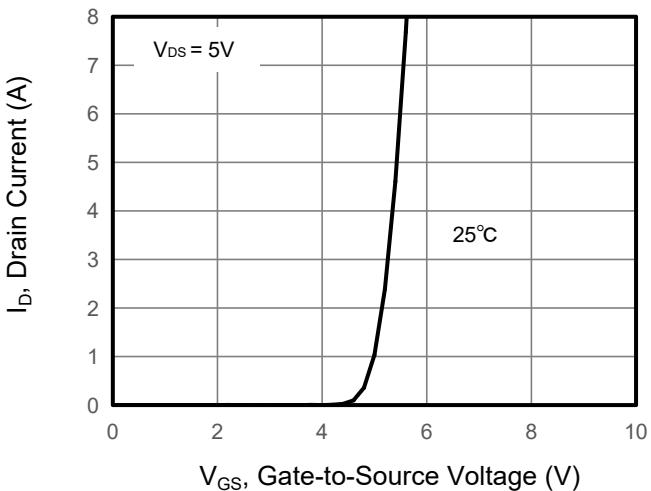


**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

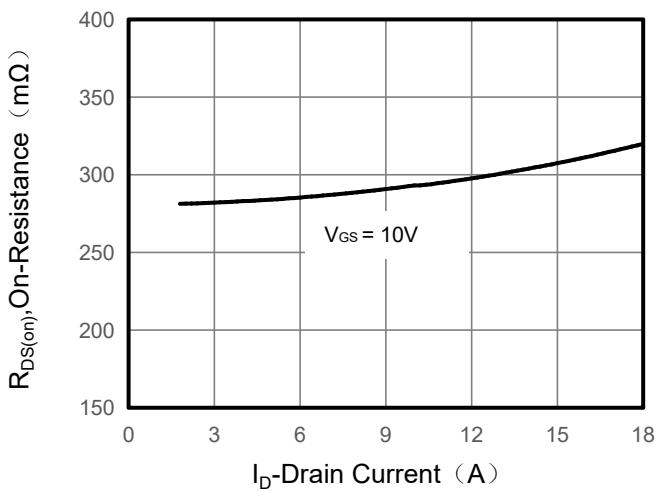
**Figure 1. Output Characteristics**



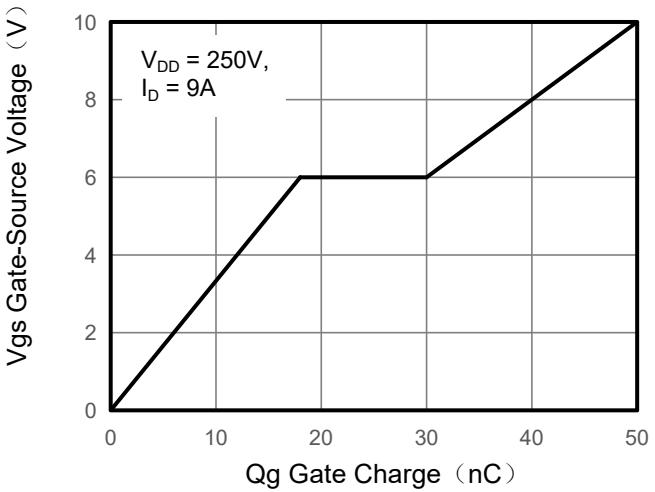
**Figure 2. Transfer Characteristics**



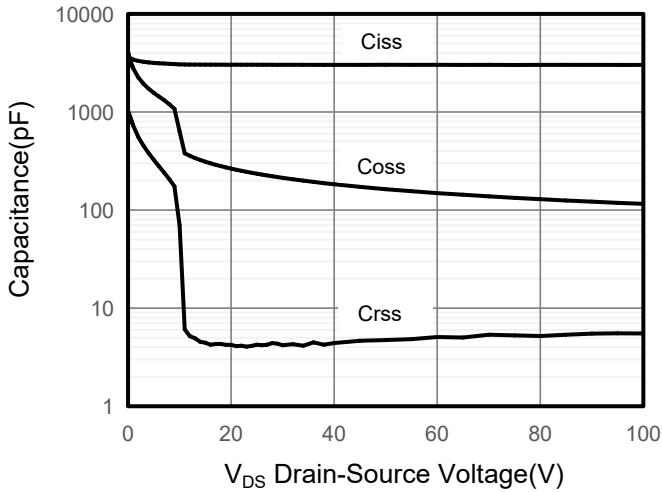
**Figure 3. Drain Source On Resistance**



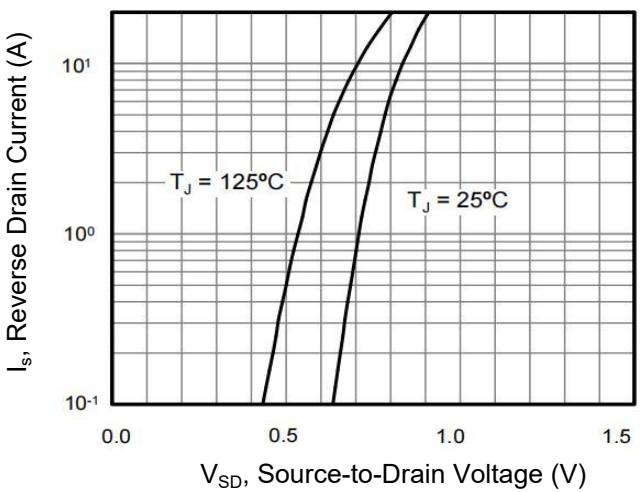
**Figure 4. Gate Charge**



**Figure 5. Capacitance**

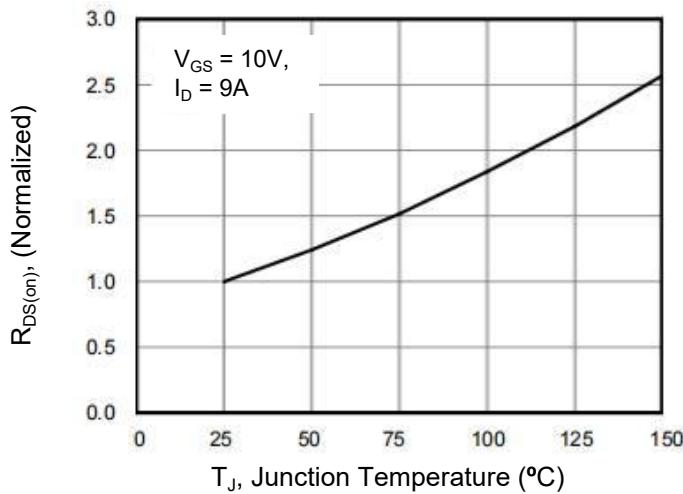


**Figure 6. Source-Drain Diode Forward**

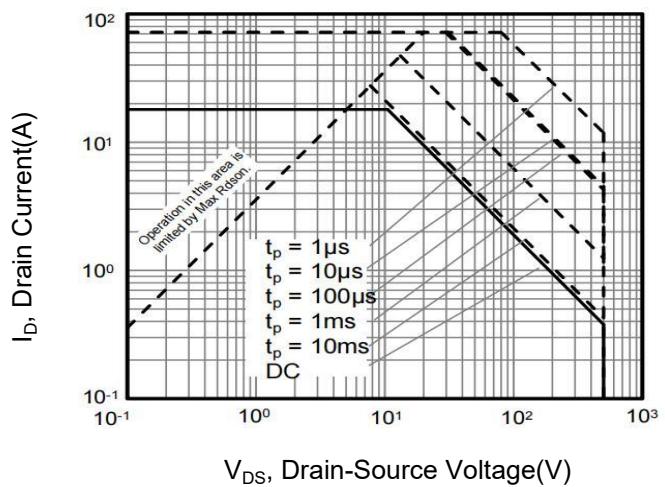


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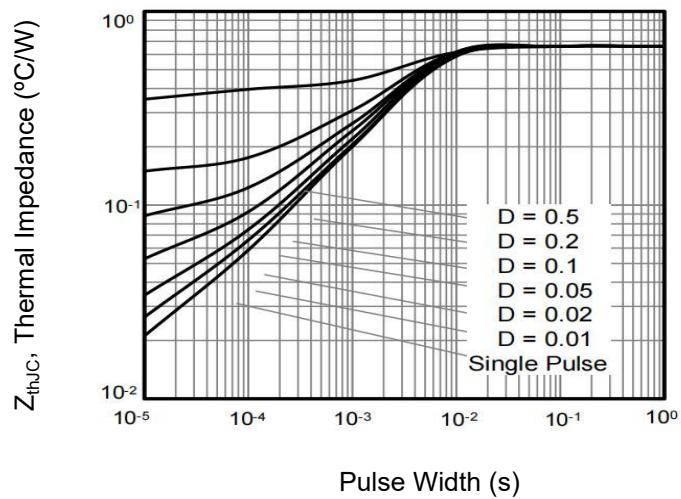
**Figure 7. Drain-Source On-Resistance**



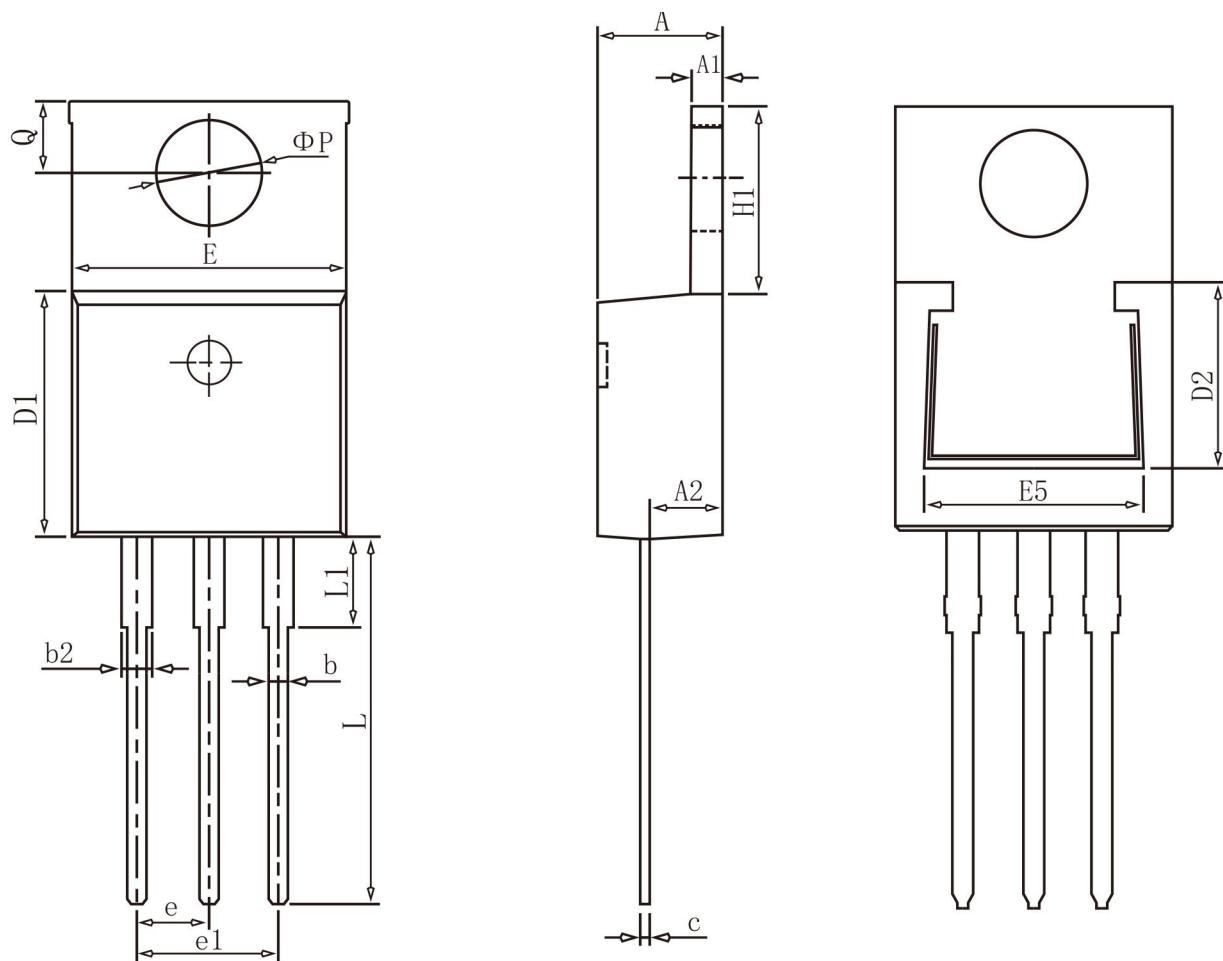
**Figure 8. Safe Operation Area**



**Figure 9. Normalized Maximum Transient Thermal Impedance**



## TO-220 Package Information



## COMMON DIMENSIONS

SYMBOL	mm		
	MIN	NOM	MAX
A	4.37	4.57	4.77
A1	1.22	1.27	1.42
A2	2.49	2.69	2.89
b	0.75	0.81	0.96
b2	1.22	1.27	1.47
c	0.30	0.38	0.48
D1	8.50	8.70	8.90
D2	5.20	—	—
E	9.86	10.16	10.36
E5	7.06	—	—
e	2.54BSC		
e1	5.08BSC		
H1	6.10	6.30	6.50
L	13.10	13.40	13.70
L1	—	3.75	4.10
Φ P	3.70	3.84	3.99
Q	2.54	2.74	2.94